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April 2016

FGA30S120P 1300 V, 30 A Shorted-anode IGBT

Features

- · High Speed Switching
- Low Saturation Voltage: $V_{CE(sat)} = 1.75 \text{ V} @ I_C = 30 \text{ A}$
- High Input Impedance
- RoHS Compliant

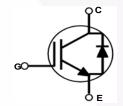
Applications

• Induction Heating, Microwave Oven

General Description

Using advanced field stop trench and shorted-anode technology, Fairchild's shorted-anode Trench IGBTs offer superior conduction and switching performances for soft switching applications. The device can operate in parallel configuration with exceptional avalanche capability. This device is designed for induction heating and microwave oven.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		Ratings	Unit
V _{CES}	Collector to Emitter Voltage		1300	V
V_{GES}	Gate to Emitter Voltage		±25	V
I _C	Collector Current	$^{\circ}$ T _C = 25 $^{\circ}$ C	60	А
	Collector Current	$@ T_C = 100^{\circ}C$	30	А
I _{CM (1)}	Pulsed Collector Current		150	А
I _F	Diode Continuous Forward Current	@ T _C = 25°C	60	A
I _F	Diode Continuous Forward Current	$@ T_C = 100^{\circ}C$	30	A
P _D	Maximum Power Dissipation	@ T _C = 25°C	348	W
. п	Maximum Power Dissipation	$^{\circ}$ @ T _C = 100°C 174		W
T _J	Operating Junction Temperature		-55 to +175	°C
T _{stg}	Storage Temperature Range		-55 to +175	°C
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 second	s	300	°C

Thermal Characteristics

Symbol Parameter		Тур.	Тур. Мах.	
R _{0JC} (IGBT) Thermal Resistance, Junction to Case			0.43	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		40	°C/W

Notes:

1: Limited by Tjmax

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA30S120P	FGA30S120P	TO-3P	Tube	N/A	N/A	30

Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	1300	-	-	V
ΔBV _{CES} / ΔT _J	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_C = 1 \text{ mA}$	-	1.3	-	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = 1300, V _{GE} = 0V	-	-	1	mA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±500	nA
On Charac	teristics			1		
V _{GE(th)}	G-E Threshold Voltage	$I_C = 30$ mA, $V_{CE} = V_{GE}$	4.5	6.0	7.5	V
	$I_C = 30A, V_{GE} = 15V$ $T_C = 25^{\circ}C$	-	1.75	2.3	V	
V _{CE(sat)}	Collector to Emitter Saturation Voltage	$I_C = 30A, V_{GE} = 15V,$ $T_C = 125^{\circ}C$	-	1.85	-	V
		I _C = 30A, V _{GE} = 15V, T _C = 175°C	-	1.9	-	V
V _{FM}	Diode Forward Voltage	$I_F = 30A, T_C = 25^{\circ}C$	-	1.7	2.2	V
PIN DIGGOTOTI		$I_F = 30A, T_C = 175^{\circ}C$	-	2.1	-	V
Dynamic C	haracteristics					
C _{ies}	Input Capacitance		-	3345	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$ f = 1MHz	-	75	-	pF
C _{res}	Reverse Transfer Capacitance	_ 1 — 11VII 12	-	60	-	pF
Switching	Characcteristics				'	
t _{d(on)}	Turn-On Delay Time		-	39	-	ns
t _r	Rise Time		-	360	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600V, I_{C} = 30A,$	-	620	-	ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$,	-	160	-	ns
E _{on}	Turn-On Switching Loss	Resistive Load, T _C = 25°C	- /	1.3	-	mJ
E _{off}	Turn-Off Switching Loss		-	1.22	-	mJ
E _{ts}	Total Switching Loss		-	2.52	-	mJ
t _{d(on)}	Turn-On Delay Time		-	38	-	ns
t _r	Rise Time		-	375	-	ns
t _{d(off)}	Turn-Off Delay Time	V_{CC} = 600V, I_{C} = 30A, R_{G} = 10 Ω , V_{GE} = 15V, Resistive Load, T_{C} = 175°C	-	635		ns
t _f	Fall Time		-	270	-	ns
E _{on}	Turn-On Switching Loss		-	1.59	- \	mJ
E _{off}	Turn-Off Switching Loss		-	1.78	-	mJ
E _{ts}	Total Switching Loss		-	3.37	-	mJ
Qg	Total Gate Charge		-	78	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 600V, I_{C} = 30A,$ $V_{GE} = 15V$	-	4.2	-	nC
Q _{gc}	Gate to Collector Charge	*GE = 10 *	-	33.3	-	nC

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

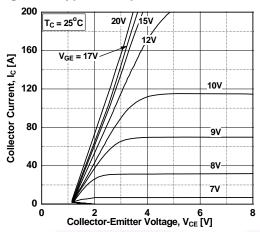


Figure 3. Typical Saturation Voltage Characteritics

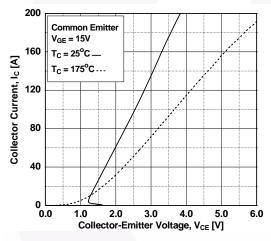


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

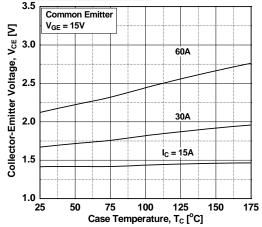


Figure 2. Typical Output Characteristics

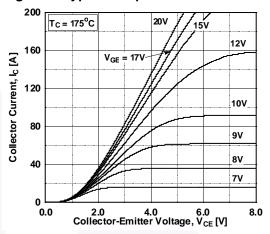


Figure 4. Transfer Characteristics

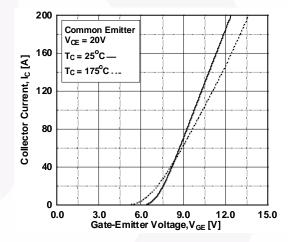
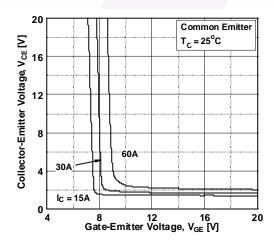


Figure 6. Saturation Voltage vs. VgE



Typical Performance Characteristics

Figure 7. Saturation Voltage vs. VgE

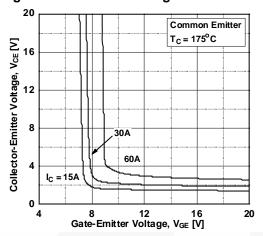


Figure 9. Gate Charge Characteristics

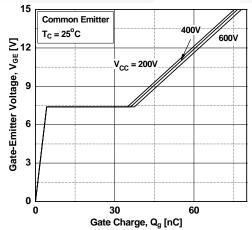


Figure 11. Turn-On Characteristics vs Gate Resistance

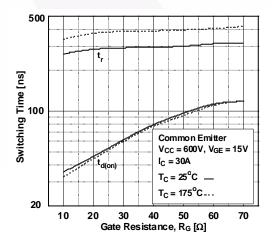


Figure 8. Capacitance Characteristics

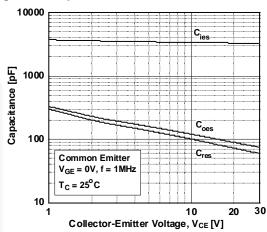


Figure 10. SOA Characteeristics

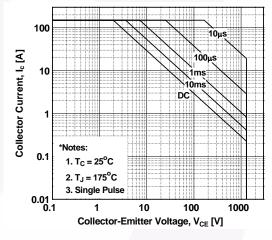
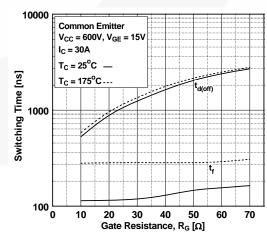


Figure 12. Turn-off Characteristics vs.
Gate Resistance



Typical Performance Characteristics

Figure 13. Turn-on Characteristics VS. Collector Current

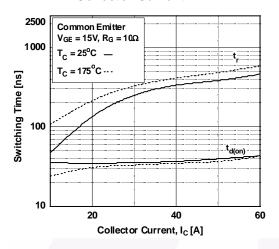


Figure 14.Turn-off Characteristics VS. Collector Current

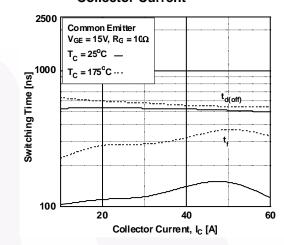


Figure 15. Switching Loss VS. Gate Resistance

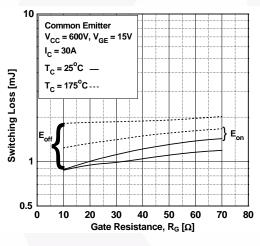


Figure 16. Switching Loss VS. Collector Current

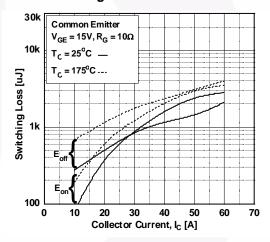


Figure 17. Turn off Switching SOA Characteristics

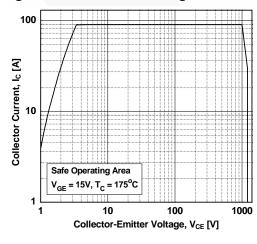


Figure 18. Forward Characteristics

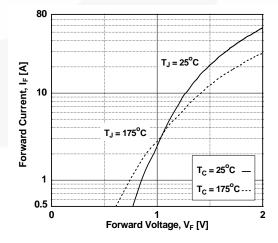
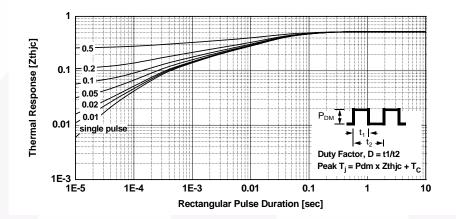
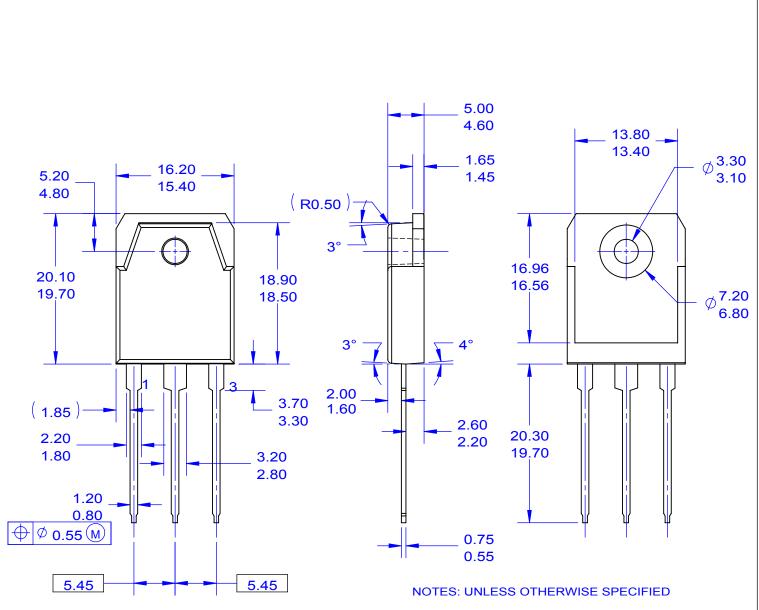
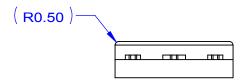


Figure 19. Transient Thermal Impedance of IGBT







- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
- E) DRAWING FILE NAME: TO3PN03AREV2.
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